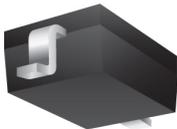


MATERIAL DECLARATION SHEET



Package Type	CDSOD323-TxxSC					
Product Line	Semiconductor Products					
Compliance Date	February 05, 2026					
RoHS Compliant	Yes	Terminal	e3	MSL	1	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy Resin	0.002962	Amorphous Silica	60676-86-0	91.689	47.530	51.838
				Epoxy Resin A	Proprietary	4.167	2.160	
				Epoxy Resin B	29690-82-2	1.414	0.733	
				Phenol Resin	Proprietary	2.146	1.113	
				Carbon Black	1333-86-4	0.583	0.302	
2	Leadframe	Copper Alloy	0.002045	Copper	7440-50-8	97.399	34.859	35.789
				Iron	7439-89-6	2.389	0.855	
				Phosphorus	7723-14-0	0.076	0.027	
				Zinc	7440-66-6	0.127	0.045	
		Silver Plating	0.000029	Silver	7440-22-4	100.000	0.508	0.508
3	Chip	Silicon	0.000424	Silicon	7440-21-3	90.696	6.729	7.420
				Nickel	7440-02-0	6.069	0.451	
				Aluminum	7429-90-5	2.860	0.212	
				Gold	7440-57-5	0.376	0.028	
4	Die Attach	Silver Epoxy	0.000066	Silver	7440-22-4	95.190	1.0993	1.155
				bisphenol-F-(epichlorohydrin); epoxy resin	9003-36-5	2.756	0.0319	
				1,4-bis(2,3 epoxypropoxy)butane	2425-79-8	1.061	0.0123	
				Aromatic polyamine	Proprietary	0.965	0.0112	
5	Bond Wires	Copper	0.000014	adipic acid	124-04-9	0.028	0.0003	0.245
				Copper	7440-50-8	98.559	0.241	
6	Lead Finish	Matte Tin	0.000174	Non - Cu element	Proprietary	1.441	0.004	3.045
				Tin	7440-31-5	100.000	3.045	
Total Weight			0.005714					

Important remarks:

1. It is responsibility of the user to verify they are accessing the latest version.